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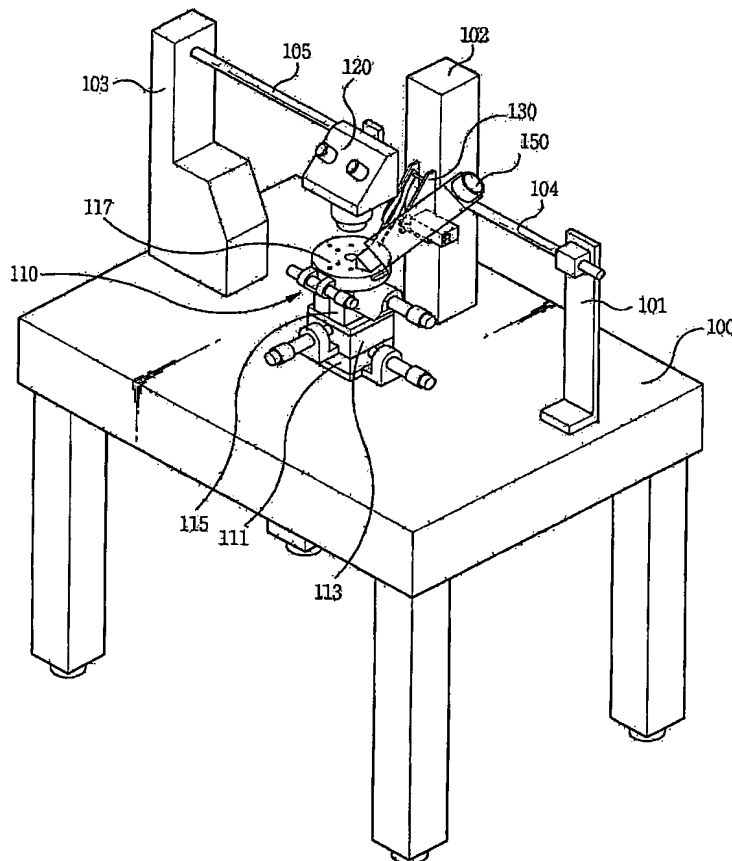
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(54) Title: PROBE POSITIONING AND BONDING DEVICE AND PROBE BONDING METHOD



(57) Abstract: Disclosed herein are a probe positioning and bonding device and a probe bonding method, and more particularly a probe positioning and bonding device used to fix probes to prescribed positions on a substrate so that a probe card used for semiconductor integrated circuit testing equipment is manufactured, and a probe bonding method using the same. The probe positioning and bonding device comprises a stage unit disposed on a working table, a microscope disposed above the stage unit while being supported by means of a first supporting member disposed on the working table, a probe fixing unit disposed above the stage unit and below the microscope while being supported by means of a second supporting member disposed on the working table, and a light source unit supported by means of a third supporting member disposed on the working table. The light source unit is disposed toward the upper part of the stage unit.



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